

Title (en)
EMBEDDED CIRCUIT IN A MEMS DEVICE

Title (de)
EINGEBETTETE SCHALTUNG IN EINER MEMS-VORRICHTUNG

Title (fr)
CIRCUIT INTÉGRÉ DANS UN DISPOSITIF MEMS

Publication
EP 2901714 A4 20160608 (EN)

Application
EP 13842019 A 20130926

Priority
• US 201261706350 P 20120927
• US 2013061873 W 20130926

Abstract (en)
[origin: WO2014052559A1] A Microelectromechanical System (MEMS) microphone includes a printed circuit board, a MEMS die, and an integrated circuit. The MEMS die disposed on a top surface of the printed circuit board. The integrated circuit is disposed at least partially within the printed circuit board and produces at least one output signal. The at least one output signal of the integrated circuit is routed directly into at least one conductor to access pads at the printed circuit board. The access pads are disposed on a bottom surface of the printed circuit board that is opposite the top surface. The integrated circuit includes conductive pads and an interface layer is disposed between the conductive pads of the integrated circuit and the printed circuit board.

IPC 8 full level
H01L 29/84 (2006.01); **H04R 1/04** (2006.01); **H04R 19/00** (2006.01); **H04R 19/04** (2006.01); **H04R 31/00** (2006.01)

CPC (source: EP)
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Citation (search report)
• [X] US 2012087521 A1 20120412 - DELAUS MICHAEL D [US], et al
• [I] JP 2012086345 A 20120510 - DAINIPPON PRINTING CO LTD
• [I] US 2011241197 A1 20111006 - THEUSS HORST [DE]
• See references of WO 2014052559A1

Designated contracting state (EPC)
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DOCDB simple family (publication)
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